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TFT | CHARACTER | UWVD | FSC | SEGMENT | CUSTOM | REPLACEMENT

TFT Display Module

Part Number E28RG12432LW2M450-R

Overview:

- 2.8-inch TFT: 240x320 (50.5x69.7)
- 3/4SPI+16/18- bit RGB
- 8/9/16/18-bit MCU
- 4-wire Resistive Touch Screen
- White LED back-light

- Transmissive
- Wide Temp
- 450 NITS
- Controller: ST7789V
- RoHS Compliant



Description

This is a color active matrix TFT (Thin Film Transistor) LCD (Liquid Crystal Display) that uses amorphous silicon TFT as a switching device. This model is composed of a transmissive type TFT-LCD Panel, driver circuit and a backlight unit. The resolution of the 2.8" TFT-LCD contains 240(RGB)x320 pixels and can display up to 262k colors.

TFT Features

Low Input Voltage: 3.3V

Display Colors: 65k/262k colors TFT Interfaces: 8/9/16/18-bit MCU

> 3/4SPI+16/18-bit RGB 3-line/4-line Serial

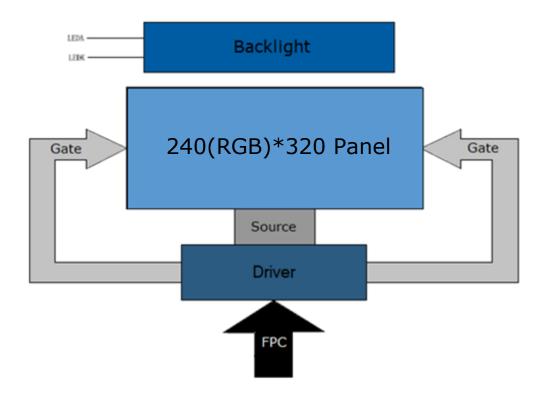
General Information Items	Specification Main Panel	Unit	Note
TFT Display area (AA)	43.20 (H) x 57.60 (V) (2.8 inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	65k/262k	colors	-
Number of pixels	240(RGB)x320	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.18 (H) x 0.18 (V)	mm	-
Viewing angle	12:00	o'clock	-
TFT Controller IC	ST7789V	-	-
LCM Interface	4-Lane LVDS	-	-
Display mode	Transmissive/ Normally White	-	-
Operating temperature	-20∼+70	°C	-
Storage temperature	-30∼+80	°C	-

Mechanical Information

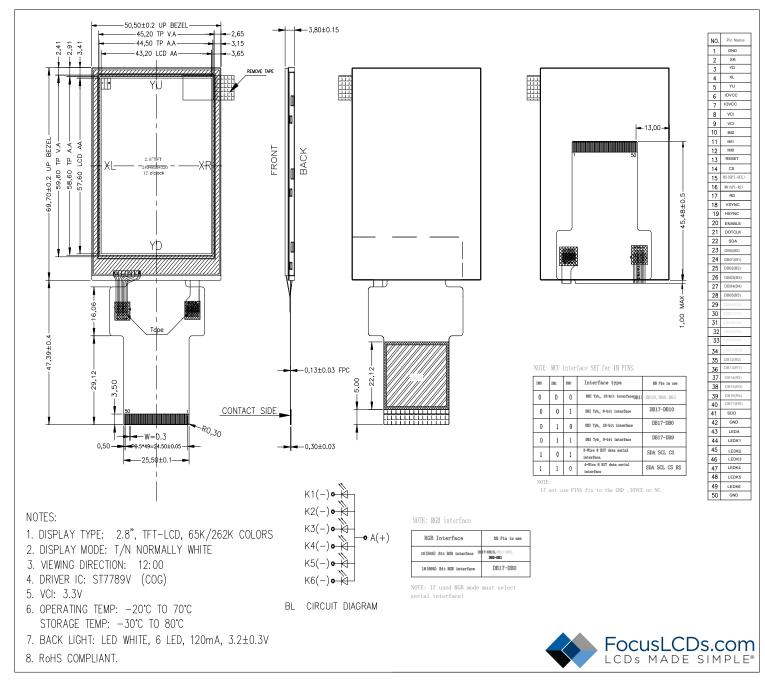
	Item	Min	Тур.	Max	Unit	Note
	Height (H)		50.50		mm	-
Module size	Vertical (V)		69.70		mm	-
0.20	Depth (D)		3.80		mm	-



1. Block Diagram



2. Outline Dimensions





3. Input Terminal Pin Assignment

Recommended TFT Connector: FH12S-50S-0.5SH(55) Recommended RTP Connector: FH33-4S-1SH(10)

NECOII	Interface IT I e	onnector: FH125-505-0.55H(55)	Recommended RTP Connector: FH33-45-15	11(10)
NO.	Symbol	Description		1/0
1	GND	Ground		
2	XR	Touch panel right glass terminal		
3	YD	Touch panel bottom film terminal		
4	XL	Touch panel left glass terminal		
5	YU	Touch panel top film terminal		
6	IOVCC	Supply voltage for IO (1.8-3.3V)		
7	IOVCC	Supply voltage for IO (1.8-3.3V)		
8	VCI	Supply voltage (3.3V)		
9	VCI	Supply voltage (3.3V)		
10	IM2	MDII parallal interface bus and carial i	nterface colors If using DCD interface, you must	
11	IM1	select which serial interface. Fix to IOV	nterface select. If using RGB interface, you must	
12	IM0	Select which serial interface. Fix to lov	ACC and GND.	
13	RESET	Reset signal of the device. Must be ap	plied to initialize chip.	
14	CS	Chip select input pin. Low enabled. Fix		
4.5	DC/CDL CCL)		ace. D/CX=1, data is selected. When D/CX=0,	
15	RS(SPI_SCL)	rface this pin is used as the data clock.		
16	MD(CDL DC)	Write signal in parallel interface. In se	rial interface it is a data pin. Data is applied at	
16	WR(SPI_RS)	the rising edge of the SCL signal. Fix to	IOVCC or GND when not used.	
17	DD	Read signal for parallel interface and N	MCU read data at the rising edge. Fix to IOVCC or	
17	RD	GND when not in use.		
18	VSYNC	Frame synchronizing signal for RGB in	erface. Fix to IOVCC or GND when not used.	
19	HSYNC	Line synchronizing signal for RGB inter	face. Fix to IOVCC or GND when not used.	
20	ENABLE	Data enable signal for RGB interface. F	ix to IOVCC or GND when not used.	
21	DOTCLK	Dot clock signal for RGB interface. Fix	to IOVCC or GND when not used.	
22	SDA	Serial input signal. The data is applied	at the rising edge of the SCL signal. Fix to IOVCC	
22	SDA	or GND when not used.		
23-40	DB0-DB17	18-bit data bus. If not used please fix t	hese pins to GND.	
41	SDO	SPI interface output pin. The data is or	utput on the falling edge of the SCL signal. Leave	
41	300	this pin open if not used.		
42	GND	Ground		
43	LEDA	Anode pin of the backlight		
44	LEDK1	Cathode pin of the backlight		
45	LEDK2	Cathode pin of the backlight		
46	LEDK3	Cathode pin of the backlight		
47	LEDK4	Cathode pin of the backlight		
48	LEDK5	Cathode pin of the backlight		
49	LEDK6	Cathode pin of the backlight		
50	GND	Ground		



4. LCD Optical Characteristics

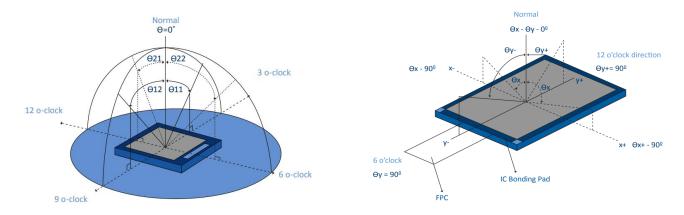
4.1 Optical Specifications

i.i Opticai sp	Decincation								
Item		Symbol	Condition	Min	Тур.	Max	Unit	Note	
Transmitta	ince	Т%			17.3		%		
Contrast R	atio	CR		400	500		%	(2)	
Daga and Time	Rising	TR			4	8	ms		
Response Time	Falling	TF		-	12	24	ms		
		Wx	V X		0.303	0.323			
	White	W_{Y}	θ=0	0.305	0.325	0.345			
	Pod	Rx	Normal viewing	0.606	0.626	0.646			
Color Filter	Red	Ry	_	0.314	0.334	0.354		(5)(6)	
Chromaticity	6	Gx	angle	0.257	0.277	0.297		(5)(6)	
	Green	Gy		0.529	0.549	0.569			
	Dluc	Bx		0.122	0.142	0.162			
	Blue	By		0.102	0.122	0.142		(5)(6)	
		ΘL		35	45				
Minusian Angla	Hor.	ΘR	CR≥10	35	45		40	(1)(6)	
Viewing Angle		ΘТ		40	50		degree	(1)(6)	
	Ver.	ΘВ		10	20		1		
Option View Di	rection			12:00				(1)	



Optical Specification Reference Notes:

(1) Definition of Viewing Angle: The viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3,9 o'clock direction and the vertical or 6,12 o'clock direction with respect to the optical axis which is normal to the LCD surface.

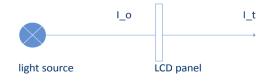


(2) Definition of Contrast Ratio (Cr): measured at the center point of panel. The contrast ratio (Cr) measured on a module, is the ratio between the luminance (Lw) in a full white area (R=G=B=1) and the luminance (Ld) in a dark area (R=G=B=0).

$$Cr = \frac{Lw}{Ld}$$

(3) Definition of transmittance (T%): The transmittance of the panel including the polarizers is measured with electrical driving. The equation for transmittance Tr is:

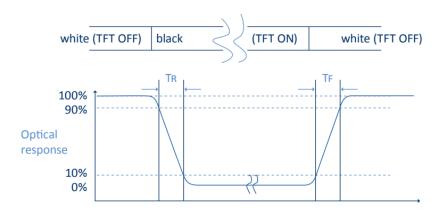
$$Tr = \frac{It}{Io} \times 100\%$$



Io = the brightness of the light source.

It = the brightness after panel transmission

(4) Definition of Response Time (Tr, Tf): The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.





(5) Definition of Color Gamut:

Measuring machine CFT-01. NTSC's Primaries: R(x,y,Y),G(x,y,Y), B(x,y,Y). FPM520 of Westar Display Technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics. The color chromaticity shall be calculated from the spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the panel.

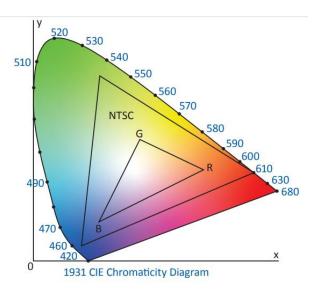
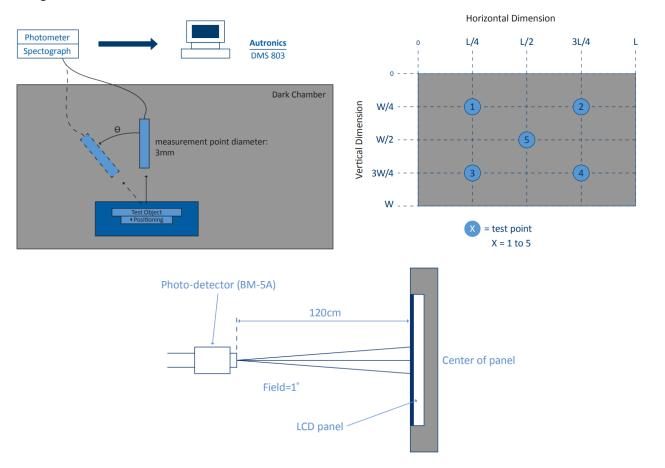


Fig. 1931 CIE chromacity diagram

Color gamut: $S = \frac{\text{Area of RGB triangle}}{\text{Area of NTSC triangle}} \times 100\%$

(6) Definition of Optical Measurement Setup:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 20 minutes.





5. TFT Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 °C, VSS=0V)

Characteristics	Symbol	Min	Max	Unit
Digital Supply Voltage	VDD	3.0	4.6	V
Digital Interface Supply Voltage	VDDIO	-0.3	4.6	V
Operating Temperature	TOP	-20	+70	°C
Storage Temperature	TST	-30	+80	°C

NOTE: If the absolute maximum rating of the above parameters is exceeded, even momentarily, the quality of the product may be degraded. Absolute maximum ratings specify the values which the product may be physically damaged if exceeded. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min	Тур.	Max	Unit	Note
Digital Supply Voltage	VDD	2.4	3.3	4.2	V	
Digital Interface Supply Voltage	VDDIO	1.65	3.3	4.2	V	
Normal Mode Current Consumption	IDD		8		mA	
Level Input Voltage	VIH	0.7VDDIO		VDDIO	V	
Level input voltage	VIL	GND	-	0.3VDDIO	V	
Level Output Voltage	VOH	0.8VDDIO		VDDIO	V	
	VOL	GND		0.2VDDIO	V	



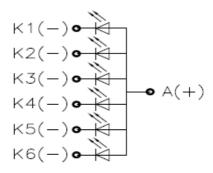
5.3 LED Backlight Characteristics

The backlight system is edge lighting type with 6 chips LED.

Item	Symbol	Min	Тур.	Max	Unit	Note
Forward Current	lF	90	120		mA	
Forward Voltage	V _F		3.2		V	
LCM Luminance	LV		450		cd/m2	Note 3
LED lifetime	Hr	50000			hour	Note1 & 2
Uniformity	AVg	80		1	%	Note 3

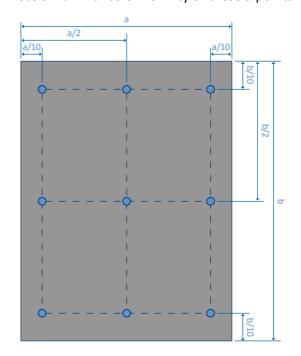
Note 1: LED lifetime (Hr) can be defined as the time in which it continues to operate under the condition: $Ta=25 \pm 3$ °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED lifetime" is defined as the module brightness decrease to 50% original brightness at $Ta=25^{\circ}C$ and IL=160mA



Backlight Circuit LED

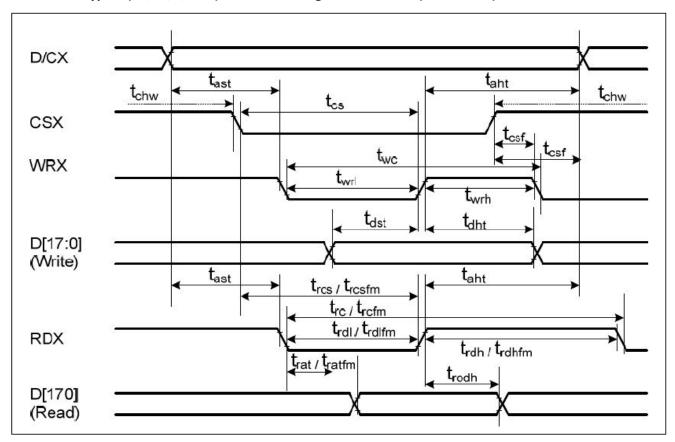
Note 3: Luminance Uniformity of these 9 points is defined as below:





6. TFT AC Characteristics

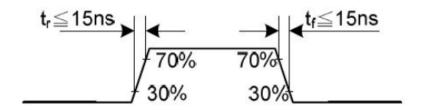
6.1 DBI Type B (18/16/9/8 bit) Interface Timing Characteristics (8080-series)



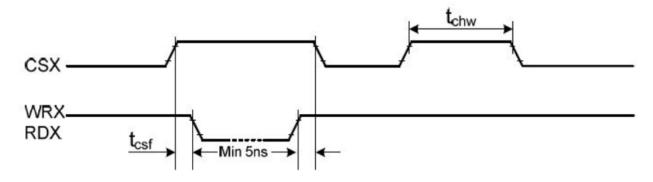
Signal	Symbol	Parameter	Min	Max	Unit	Description	
D/CV	tast	Address setup time	0	-	ns		
D/CX	that	Address hold time (Write/Read)	0	-	ns		
	tchw	CSX "H' pulse width	0	-	ns		
	tcs	Chip select setup time (Write)	15	-	ns		
CSX	trcs	Chip select setup time (Read ID)	45	-	ns		
	trcsfm	Chip select setup time (Read FM)	355	-	ns		
	tcsf	Chip select wait time (Write/Read)	0	-	ns		
	twc	Write cycle	50	-	ns		
WRX	twrh	Write control pulse H duration	15	-	ns		
	twrl	Write control pulse L duration	15	-	ns		
	trcfm	Read cycle (FM)	450	-	ns	When read from	
RDX(FM)	trdhfm	Read control H duration (FM)	90	-	ns		
	trdlfm	Read control L duration (FM)	355	-	ns	frame memory	
	trc	Read cycle (ID)	160	-	ns		
RDX(ID)	trdh	Read control pulse H duration	90	-	ns	When read ID data	
	trdl	Read control pulse L duration	45	-	ns		
DD[47.0]	tdst	Write data setup time	10	-	ns	F	
DB[17:0]	tdht	Write data hold time	10	-	ns	For maximum,	
DB[15:0] DB[8:0]	trat	Read access time	1	40	ns	CL=30pF For minimum,	
DB[8.0] DB[7:0]	tratfm	Read access time	1	340	ns	CL=8pF	
[ט./]טט	trod	Read output disable time	20	80	ns	CL-ohi	



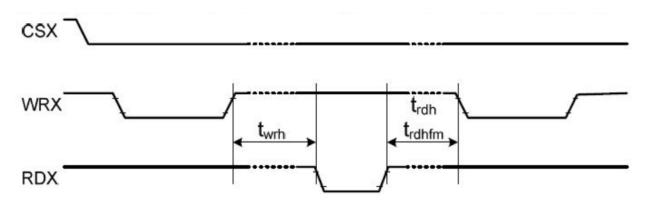
Note: (1) Ta = -30 to 70° , IOVCC = 1.65V to 3.6V, VCI = 2.5V to 3.6V, AGND = DGND = 0V



(2) Logic high and low levels are specified as 30% and 70% of IOVCC for input signals.

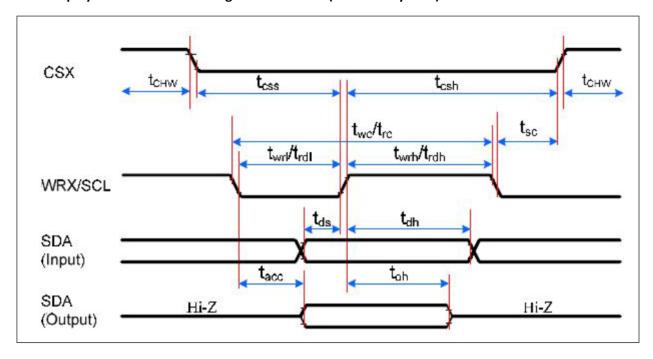


(3) Logic high and low levels are specified as 30% and 70% of IOVCC for input signals.





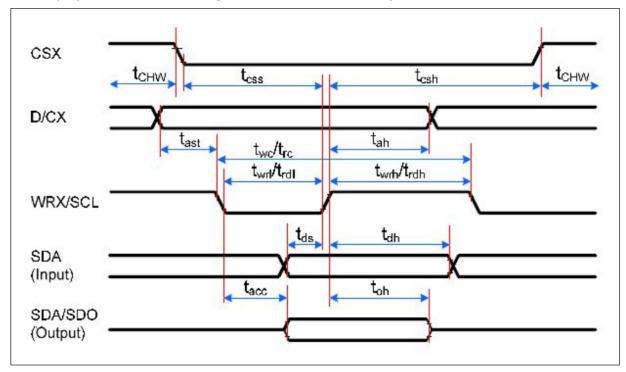
6.2 Display Serial Interface Timing Characteristics (3-line SPI system)



Signal	Symbol	Parameter	Min	Max	Unit	Description
	tsc	SCL-CSX	15	-	ns	
CSX	tchw	CSX H pulse width	40	-	ns	
CSA	tcss	Chip select time (Write)	60	-	ns	
	tcsh	Chip select hold time (Read)	65	-	ns	
	twc	Serial clock cycle (Write)	66	-	ns	
	twrh	SCL H pulse width (Write)	15	-	ns	
SCL	twrl	SCL L pulse width (Write)	15	-	ns	
SCL	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL H pulse width (Read)	60	-	ns	
	trdl	SCL L pulse width (Read)	60	-	ns	
SDA	tds	Data setup time (Write)	10	-	ns	When read ID data
SDA	tdh	Data hold time (Write)	10	-	ns	When read iD data
SDA/SDO	tacc	Access time (Read)	10	50	ns	For max, CL=30pF
(Output)	toh	Output disale time (Read)	15	50	ns	For mini, CL=8pF



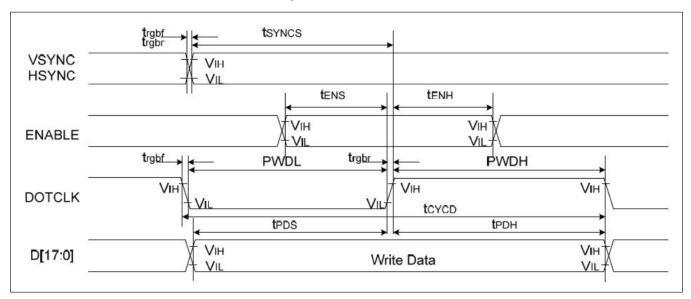
6.3 Display Serial Interface Timing Characteristics (4-line SPI system)



Signal	Symbol	Parameter	Min	Max	Unit	Description
	tsc	SCL-CSX	15	-	ns	
CCV	tchw	CSX H pulse width	40	-	ns	
CSX	tcss	Chip select time (Write)	60	-	ns	
	tcsh	Chip select hold time (Read)	65	-	ns	
	twc	Serial clock cycle (Write)	66	-	ns	
	twrh	SCL H pulse width (Write)	15	-	ns	
CCI	twrl	SCL L pulse width (Write)	15	-	ns	
SCL	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL H pulse width (Read)	60	-	ns	
	trdl	SCL L pulse width (Read)	60	-	ns	
D/CV	tas	D/CX setup time	10	-	ns	
D/CX	tah	D/CX hold time (Write/Read)	10	-	ns	
CDA	tds	Data setup time (Write)	10	-	ns	
SDA	tdh	Data hold time (Write)	10	-	ns	
SDA/SDO	tacc	Access time (Read)	10	50	ns	For max, CL=30pF
(Output)	toh	Output disale time (Read)	15	50	ns	For mini, CL=8pF

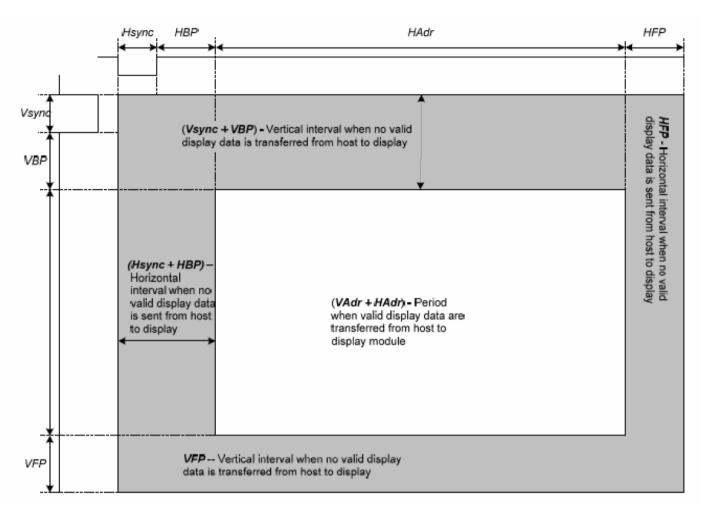


6.4 Parallel 18/16-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter	Min	Max	Unit	Description
VSYNC/	tSYNCS	VSYNC/HSYNC setup time	15	-	ns	
HSYNC	tSYNCH	VSYNC/HSYNC hold time	15	-	ns	
ENLABLE	tENS	ENABLE setup time	15	-	ns	
ENABLE	tENH	ENABLE hold time	15	-	ns	
DB[17:0]	tPOS	Data setup time	15	-	ns	18/16-bit bus RGB
DB[17.0]	tPDH	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level period	15	-	ns	
DOTCLY	PWDL	DOTCLK low-level period	15	-	ns	
DOTCLK	tCYCD	DOTCLK cycle time	66	-	ns	
	trgbr,trgbf	DOTCLK, HSYNC, VSYNC rise/fall time	-	15	ns	





Parameters	Symbols	Min	Тур.	Max	Units
PCLK cycle	PCLKcyc	100	80	66.6	Ns
Horiontal synchronization	Hsync	3	3	-	PCLK
Horizontal back porch	HBP	3	3	-	PCLK
Horizontal address	HAdr	-	320	-	PCLK
Horizontal front porch	HFP	3	3	-	PCLK
Vertical synchronization	Vsync	2	2	-	Line
Vertical back porch	VBP	2	2	-	Line
Vertical address	Vadr	-	480	-	Line
Vertical front porch	VFP	2	2	-	Line
Vertical frequency(*)		50	60	80	Hz
Horizontal frequency(*)		-	33	-	kHz
PCLK frequency(*)		10	12.5	15	MHz

Notes:

- (1) Vertical period (one frame) shall be equal to the sum of Vsync + VBP + VAdr +VFP.
- (2) Horizontal period (one line) shall be equal to the sum Hsync + HBP +HAdr + HFP.
- (3) Control signals PCLK and Hsync shall be transmitted as specified at all times while valid pizels are transferred between the host processor and the display module.



6.5 Reset Timing

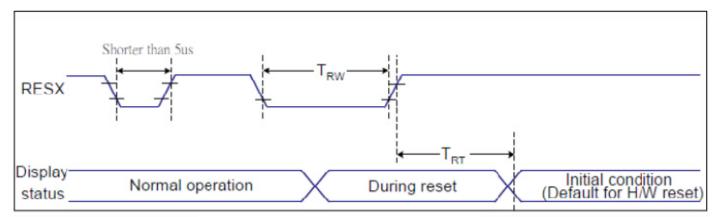


Figure 6.5: Reset Timing Diagram

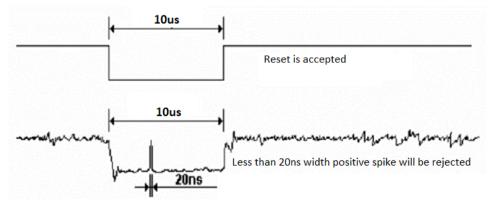
Related Pins	Symbol	Parameter	Min	Max	Unit
	TRW	Reset pulse duration	10	-	us
RESX	TRT Reset cancel	Danet samuel	-	5 (Note 1,5)	ms
			120 (Note 1, 6, 7)	ms	

Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5ms after a rising edge of RESX.
- 2. Spike due to an electrostatic discharge on RESX line does not because irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9 us	Reset starts

- 3. During the resetting period, the display will be blanked (the display is entering blanking sequence, which maximum time is 120ms, when reset starts in Sleep Out mode. The display remains the blank state in Sleep in mode) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- 7. It is necessary to wait 5ms after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120ms.



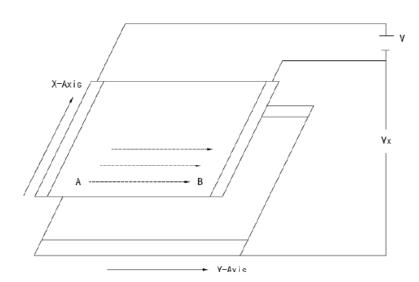
7. TP Feature

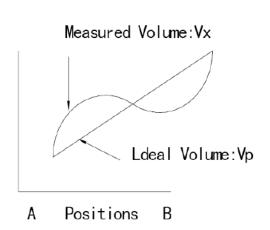
7.1 Conditions of Use and Storage

Item	Condition	Note
Temperature range upon operation	Humidity: 20%-90% non-dew, condensation -20°C~70°C	In a simple substance
Temperature range upon storage	Humidity: 20%-90% non-dew, condensation -30°C~80°C	In a simple substance

7.2 Electrical Property

Item	Value	Note	
Maximum voltage	DC5V		
	X direction (film side): 200-600 Ω		
Resistance between terminal	Y direction (glass side): 300-900 Ω		
Insulation resistance	DC 25V, 20MΩ or above	Connect X + ~X and Y+ ~Y, apply 25VDC	
Chattering	10ms or below	Between X and Y for perform measurements	
Rating	Voltage is 5V DC		







7.3 Mechanical Property

Item	Value		Note	
Input method	Used of an exclusive pen or finger			
	Exclusive pen	60-100g or below	Operation and measurement with a pen must be carried out under the following tip conditions: Stylus pen material: POM (ployacetal) Tip: Diameter 3.0mm, SR 0.8 mm	
Load upon operation	Finger	60-100g or below	Operation and measurement with a pen must be carried out under the following tip conditions: Stylus pen material: Silicon rubber (Hardness: 30°Hs) Tip: Diameter 12.0mm, SR 12.5 mm	
Surface hardness	Pencil Hardness: 3H or above		It complies with the way of test method JIS K5400	

7.4 Optical Property

714 Optical Property			
Item	Performance	Note	
Total light transmittance	80% or above	JIS K7105	
Haze	5% or below	JIS K7136	
Film specification	Polished type with hard coated surface		



8. Cautions and Handling Precautions

8.1 Handling and Operating the Module

- 1. When the module is assembled, it should be attached to the system firmly. Do not warp or twist the module during assembly work.
- 2. Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- 3. Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- 4. Do not allow drops of water or chemicals to remain on the display surface. If you have the droplets for a long time, staining and discoloration may occur.
- 5. If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- 6. The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane. Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- 7. If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- 8. Protect the module from static; it may cause damage to the CMOS ICs.
- 9. Use fingerstalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- 10. Do not disassemble the module.
- 11. Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- 12. Pins of I/F connector shall not be touched directly with bare hands.
- 13. Do not connect, disconnect the module in the "Power ON" condition.
- 14. Power supply should always be turned on/off by the item Power On Sequence & Power Off Sequence

8.2 Storage and Transportation.

- 1. Do not leave the panel in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- 2. Do not store the TFT-LCD module in direct sunlight.
- 3. The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- 4. It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module. In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- 5. This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.